

CHIPBOND

頤邦科技

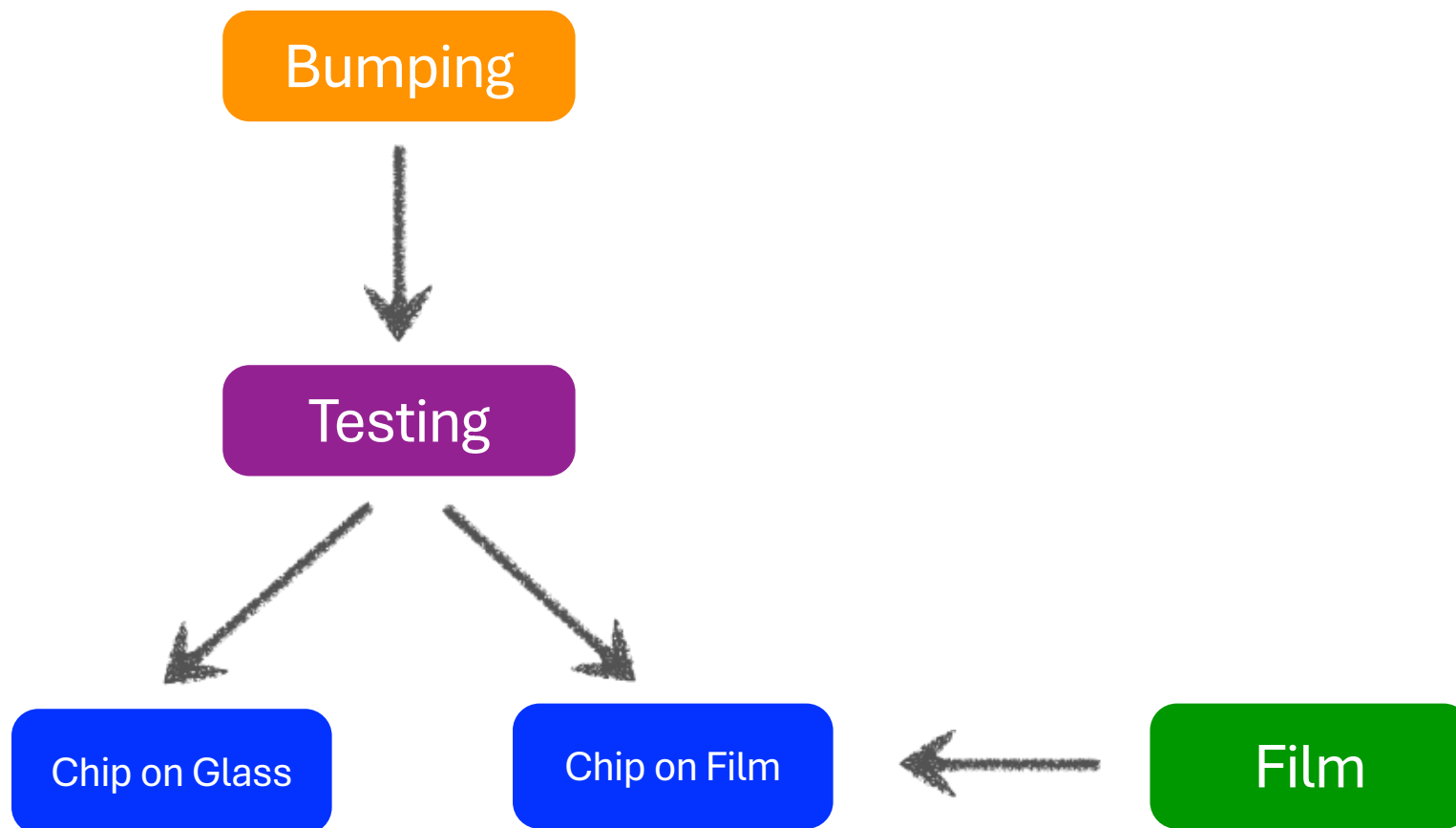
2026 Q2

金凸塊

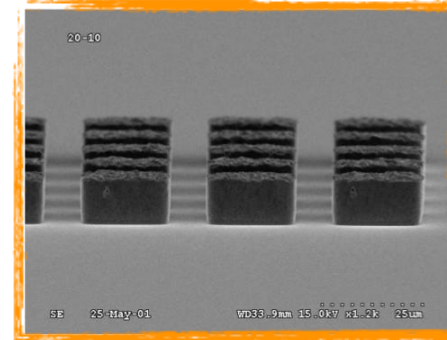
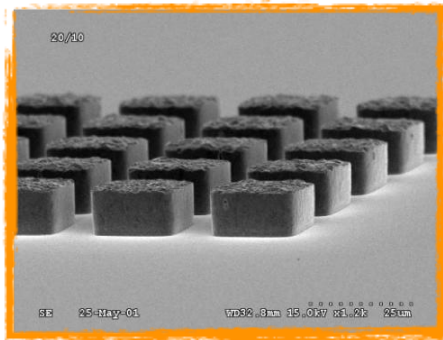


驅動 IC
射頻前端
射頻識別
矽光子
指紋辨識

產品與製程



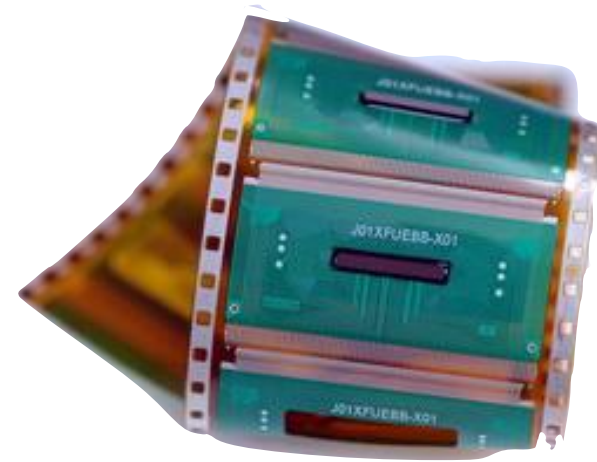
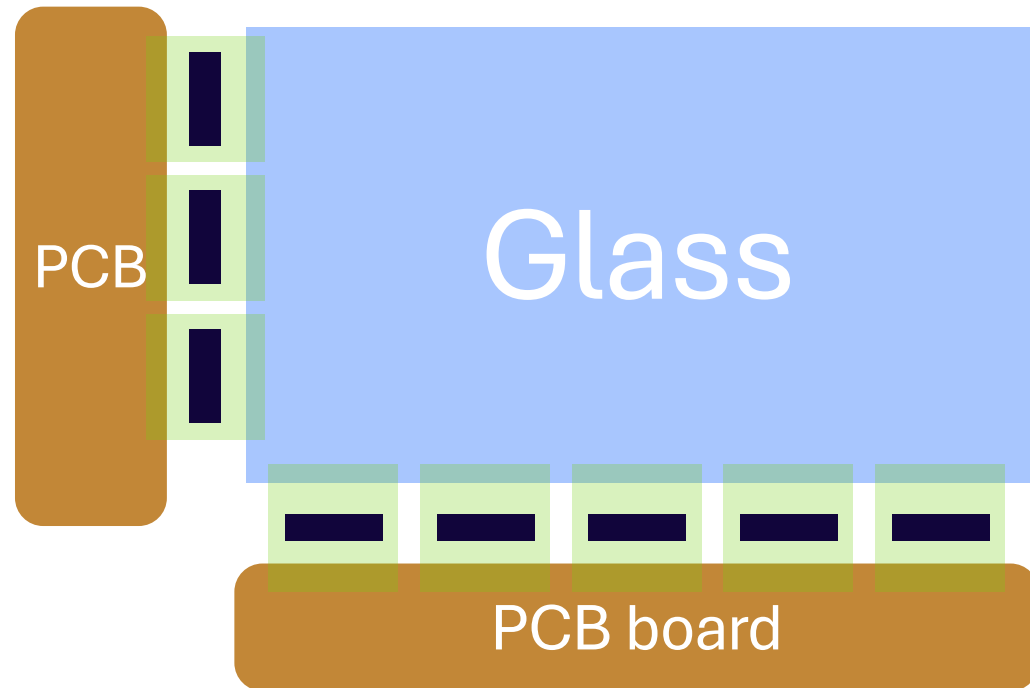
金凸塊



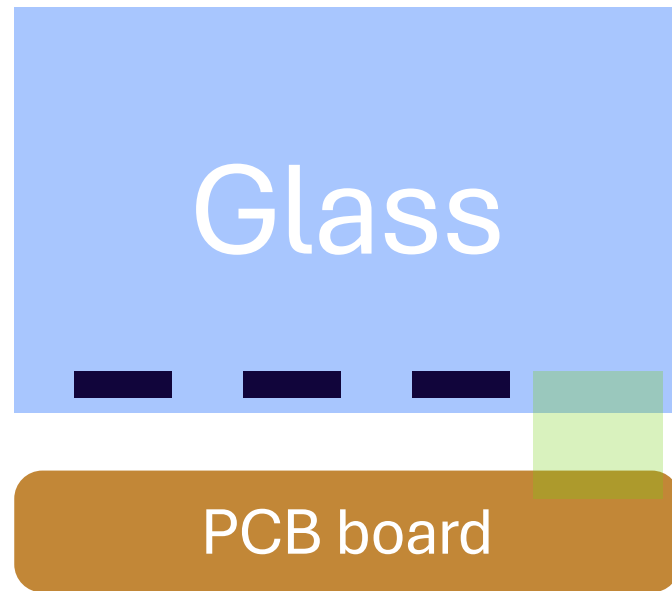
Interconnect between IC and Substrate

Has to be gold for driver IC

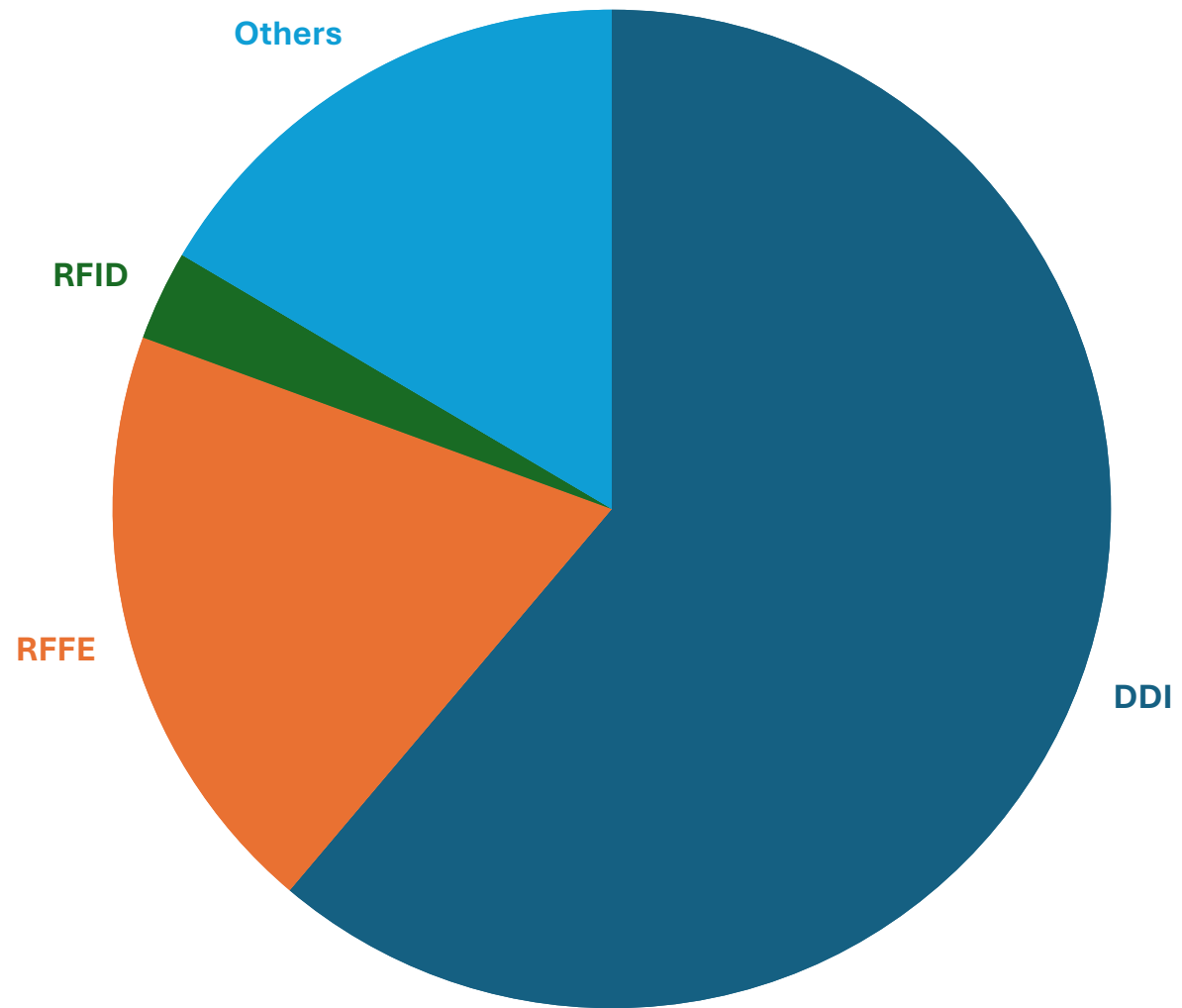
CHIP ON FILM



CHIP ON GLASS



	TV	Phone	NB/PC	RF	SiPho
Bumping	8"	12"	8"	8"	8"
Testing	v	v	v	v	
Chip on Glass		v	v		
Chip on Film	v	v			
Film	v	v			



2025

